



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
 ASSEMBLY VARIANT: [No Variations]

| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| PCB VIEWED FROM TOP SIDE | BOARD #: TIDA-01399 | REV: E1 | SVN REV: Not In VersionControl |
| IGNORE -> | | | |
| PLOT NAME = Top Assembly Drawing | GENERATED : 4/3/2017 | 1:10:17 PM | TEXAS INSTRUMENTS |

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COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
ASSEMBLY VARIANT: [No Variations]

| | | | |
|-------------------------------------|----------------------|------------|--------------------------------|
| PCB VIEWED FROM BOTTOM SIDE | BOARD #: TIDA-01399 | REV: E1 | SVN REV: Not In VersionControl |
| | IGNORE -> | | |
| PLOT NAME = Bottom Assembly Drawing | GENERATED : 4/3/2017 | 1:10:19 PM | TEXAS INSTRUMENTS |

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